

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6209183

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHEN-SHIEN CHEN	06/21/2020
	MING-DA CHENG	06/15/2020
	MING-CHIH YEW	04/22/2020
	YU-TSE SU	06/22/2020
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.	
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	15901355	
CORRESPONDENCE DATA		
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NAME OF SUBMITTER:	ANTHONY KING	
SIGNATURE:	/Anthony King/	
DATE SIGNED:	07/20/2020	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS, I(we), CHEN, CHEN-SHIEN, CHENG, MING-DA, YEW, MING-CHIH and SU, YU-TSE whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

☐ United States Design Patent was

☐ executed on:

☒ filed on: 21 February 2018

Serial No.: 15/901,355

☐ established by PCT International Patent Application No.:

filed:

designating the

United States of America

☐ issued on _____ as U.S. Patent No.:

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD., whose post office address is NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof, and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Assignor Name CHEN, CHEN-SHIEN <i>Chen Chen Shien</i>	Address 6F, NO.98, WENXIAO ST., ZHUBEI CITY, HSINCHU COUNTY 302, TAIWAN (R.O.C.)
Signature of Assignor (X) <i>Chen Chen Shien</i>	Date of Signature (X) <i>2018. 6. 21</i>
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (optional)

Assignor Name CHENG, MING-DA	Address 8F. NO. 35, SHENGLI 6TH ST., SHIH-SING VILLAGE, JHUBEI CITY, HSINCHU COUNTY, TAIWAN (R.O.C)
Signature of Assignor (X) <i>Cheng Ming-Da</i>	Date of Signature (X) <i>2020 6/15</i>
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name YEW, MING-CHIH	Address NO.16, ALY. 16, LN. 162, GAOCUI RD., EAST DIST., HSINCHU CITY 300, TAIWAN (R.O.C.)
Signature of Assignor (X) <i>Ming-Chih Yew</i>	Date of Signature (X) <i>2020 06 22</i>
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name SU, YU-TSE	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN (R.O.C.)
Signature of Assignor (X) <i>Su Yu-Tse</i>	Date of Signature (X) <i>2020 06 22</i>
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)